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TECHNICAL REPORT



Roadmap of optical circuit boards and their related packaging technologies

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

ROADMAP OF OPTICAL CIRCUIT BOARDS AND THEIR RELATED PACKAGING TECHNOLOGIES

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IEC 62658, which is a technical report, has been prepared by IEC technical committee 86: Fibre optics.

The text of this technical report is based on the following documents:

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Full information on the voting for the approval of this technical report can be found in the report on voting indicated in the above table.

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ROADMAP OF OPTICAL CIRCUIT BOARDS AND THEIR RELATED PACKAGING TECHNOLOGIES

1 Scope

This Technical Report covers the roadmap of optical circuit boards, and its related packaging technologies including optical circuit board connectors and optical modules on boards.